

# Field Stop Trench IGBT with Soft Fast Recovery Diode

120 A, 650 V

## AFGY120T65SPD

AFGY120T65SPD which is AEC Q101 qualified offers very low conduction and switch losses for a high efficiency operation in various applications, rugged transient reliability and low EMI.

Meanwhile, this part also offers an advantage of outstanding parallel operation performance with balance current sharing.

### Features

- AEC-Q101 Qualified
- Very Low Saturation Voltage:  $V_{CE(Sat)} = 1.6 \text{ V (Typ.) @ } I_C = 120 \text{ A}$
- Maximum Junction Temperature:  $T_J = 175^\circ\text{C}$
- Positive Temperature Co-efficient for Easy Parallel Operating
- Tight Parameter Distribution
- High Input Impedance
- 100% of the Parts are Tested for  $I_{LM}$
- Short Circuit Ruggedness
- Co-packed with Soft Fast Recovery Diode

### Typical Applications

- Traction Inverter for HEV/EV
- Auxiliary DC/AC Converters
- Motor Drives
- Other Power-Train Applications Requiring High Power Switch

### MAXIMUM RATINGS

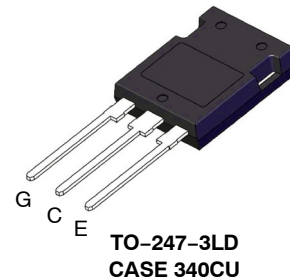
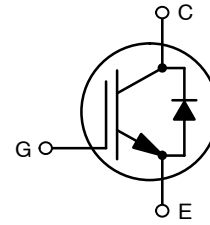
Rating	Symbol	Value	Unit
Collector-to-Emitter Voltage	$V_{CES}$	650	V
Gate-to-Emitter Voltage	$V_{GES}$	$\pm 20$	V
Transient Gate-to-Emitter Voltage		$\pm 30$	V
Collector Current (Note 1) @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	$I_C$	160 120	A
Pulsed Collector Current	$I_{LM}$	360	A
Pulsed Collector Current	$I_{CM}$	360	A
Diode Forward Current (Note 1) @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	$I_F$	160 120	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	$P_D$	714 357	W
Short Circuit Withstand Time @ $T_C = 25^\circ\text{C}$	SCWT	6	$\mu\text{s}$
Voltage Transient Ruggedness (Note 2)	$dV/dt$	10	V/ns
Operating Junction / Storage Temperature Range	$T_J, T_{STG}$	-55 to +175	$^\circ\text{C}$
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	$T_L$	265	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

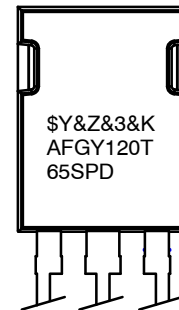
1. Value limit by bond wire

2.  $V_{CC} = 400 \text{ V}$ ,  $V_{GE} = 15 \text{ V}$ ,  $I_C = 360 \text{ A}$ , Inductive Load

120 A, 650 V,  
 $V_{CESat} = 1.6 \text{ V}$



### MARKING DIAGRAM



\$Y = onsemi Logo  
 &Z = Assembly Plant Code  
 &3 = Date Code (Year & Week)  
 &K = Lot Traceability Code  
 AFGY120T65SPD = Specific Device Code

### ORDERING INFORMATION

Device	Package	Shipping
AFGY120T65SPD	TO-247-3LD	30 Units / Tube

# AFGY120T65SPD

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{\theta JC}$	0.21	°C/W
Thermal resistance junction-to-case, for Diode	$R_{\theta JC}$	0.32	
Thermal resistance junction-to-ambient	$R_{\theta JA}$	40	

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	$BV_{CES}$	650	–	–	V
Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	$\frac{\Delta BV_{CES}}{\Delta T_J}$	–	0.6	–	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, V_{CE} = 650\text{ V}$	$I_{CES}$	–	–	40	μA
Gate leakage current, collector-emitter short-circuited	$V_{GE} = 20\text{ V}, V_{CE} = 0\text{ V}$	$I_{GES}$	–	–	±250	nA

### ON CHARACTERISTICS

Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_C = 120\text{ mA}$	$V_{GE(th)}$	4.3	5.3	6.3	V
Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 120\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 120\text{ A}, T_J = 175^\circ\text{C}$	$V_{CE(sat)}$	– –	1.6 2.15	2.05 –	V

### DYNAMIC CHARACTERISTICS

Input capacitance	$V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	$C_{ies}$	–	4930	–	pF
Output capacitance		$C_{oes}$	–	375	–	
Reverse transfer capacitance		$C_{res}$	–	42	–	
Internal Gate Resistance	$f = 1\text{ MHz}$	$R_G$	–	3	–	Ω
Gate charge total	$V_{CE} = 400\text{ V}, I_C = 120\text{ A}, V_{GE} = 15\text{ V}$	$Q_g$	–	125	187	nC
Gate-to-emitter charge		$Q_{ge}$	–	38	–	
Gate-to-collector charge		$Q_{gc}$	–	40	–	

### SWITCHING CHARACTERISTICS, INDUCTIVE LOAD

Turn-on delay time	$T_J = 25^\circ\text{C}, V_{CC} = 400\text{ V}, I_C = 120\text{ A}, R_G = 5.0\text{ }\Omega, V_{GE} = 15\text{ V}, \text{Inductive Load}$	$t_{d(on)}$	–	40	–	ns
Rise time		$t_r$	–	104	–	
Turn-off delay time		$t_{d(off)}$	–	80	–	
Fall time		$t_f$	–	116	–	
Turn-on switching loss		$E_{on}$	–	6.6	–	mJ
Turn-off switching loss		$E_{off}$	–	3.8	–	
Total switching loss		$E_{ts}$	–	10.4	–	
Turn-on delay time	$T_J = 175^\circ\text{C}, V_{CC} = 400\text{ V}, I_C = 120\text{ A}, R_G = 5.0\text{ }\Omega, V_{GE} = 15\text{ V}, \text{Inductive Load}$	$t_{d(on)}$	–	36	–	ns
Rise time		$t_r$	–	112	–	
Turn-off delay time		$t_{d(off)}$	–	92	–	
Fall time		$t_f$	–	160	–	
Turn-on switching loss		$E_{on}$	–	10.5	–	mJ
Turn-off switching loss		$E_{off}$	–	4.9	–	
Total switching loss		$E_{ts}$	–	15.4	–	

# AFGY120T65SPD

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted) (Continued)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
<b>DIODE CHARACTERISTIC</b>						
Diode Forward Voltage	$I_F = 120\text{ A}, T_J = 25^\circ\text{C}$	$V_{FM}$	–	1.4	1.7	V
	$I_F = 120\text{ A}, T_J = 175^\circ\text{C}$		–	1.35	–	
Reverse Recovery Energy	$I_F = 120\text{ A}, dI_F/dt = 1000\text{ A}/\mu\text{s}, V_{CE} = 400\text{ V}, T_J = 25^\circ\text{C}$	$E_{rec}$	–	428	–	$\mu\text{J}$
	$I_F = 120\text{ A}, dI_F/dt = 1000\text{ A}/\mu\text{s}, V_{CE} = 400\text{ V}, T_J = 175^\circ\text{C}$		–	2026	–	
Diode Reverse Recovery Time	$I_F = 120\text{ A}, dI_F/dt = 1000\text{ A}/\mu\text{s}, V_{CE} = 400\text{ V}, T_J = 25^\circ\text{C}$	$T_{rr}$	–	107	–	ns
	$I_F = 120\text{ A}, dI_F/dt = 1000\text{ A}/\mu\text{s}, V_{CE} = 400\text{ V}, T_J = 175^\circ\text{C}$		–	203	–	
Diode Reverse Recovery Charge	$I_F = 120\text{ A}, dI_F/dt = 1000\text{ A}/\mu\text{s}, V_{CE} = 400\text{ V}, T_J = 25^\circ\text{C}$	$Q_{rr}$	–	2237	–	nC
	$I_F = 120\text{ A}, dI_F/dt = 1000\text{ A}/\mu\text{s}, V_{CE} = 400\text{ V}, T_J = 175^\circ\text{C}$		–	8155	–	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

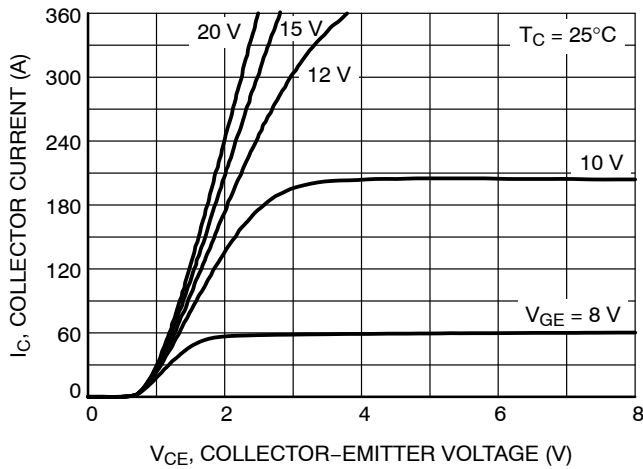


Figure 1. Typical Output Characteristics

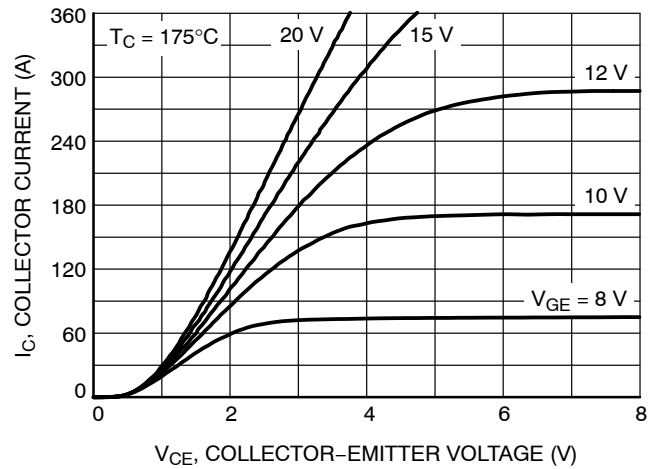


Figure 2. Typical Output Characteristics

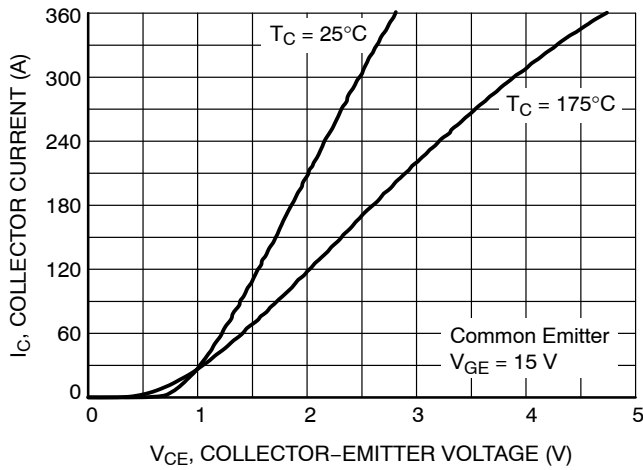


Figure 3. Typical Saturation Voltage

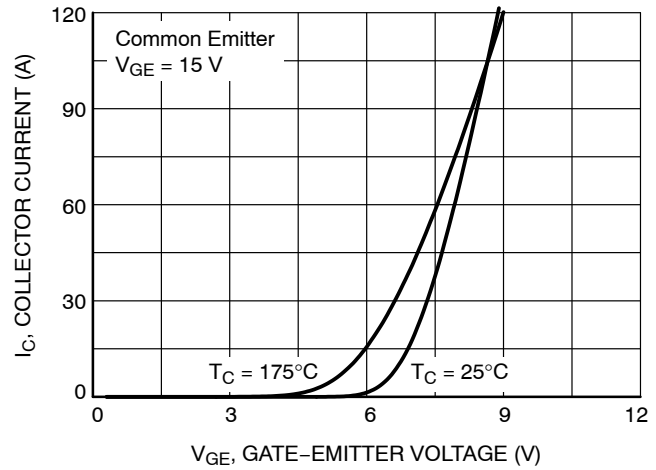


Figure 4. Transfer Characteristics

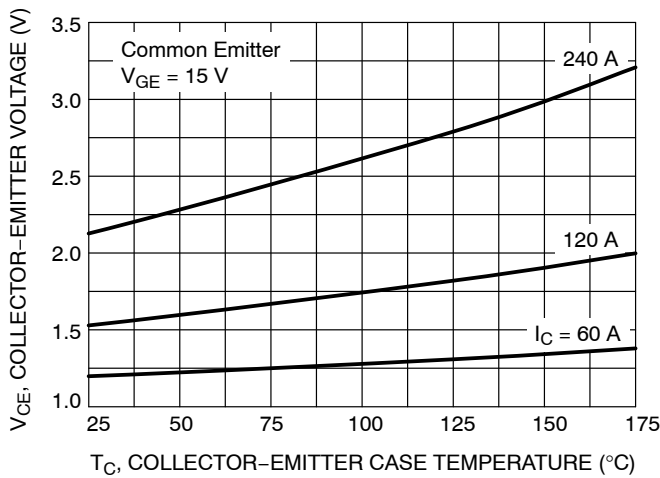


Figure 5. Saturation Voltage vs. Case Temperature

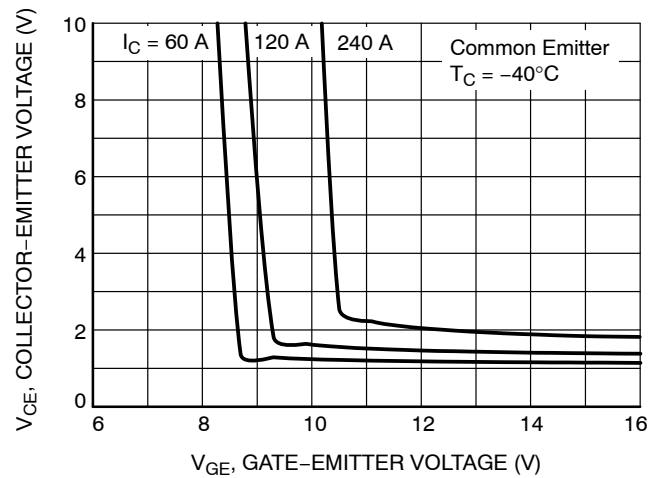


Figure 6. Saturation Voltage vs.  $V_{GE}$

TYPICAL CHARACTERISTICS

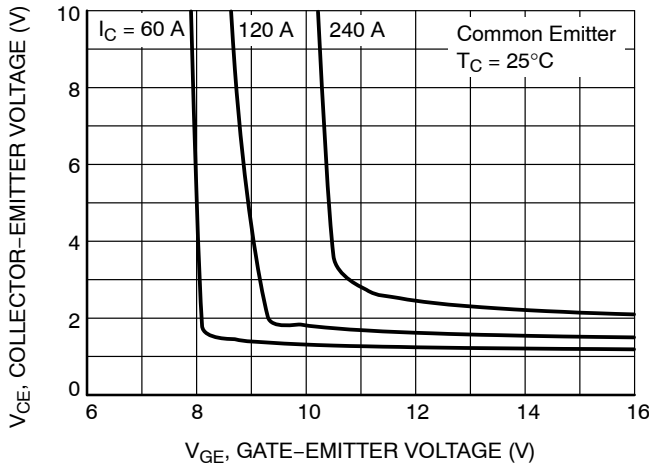


Figure 7. Saturation Voltage vs.  $V_{CE}$

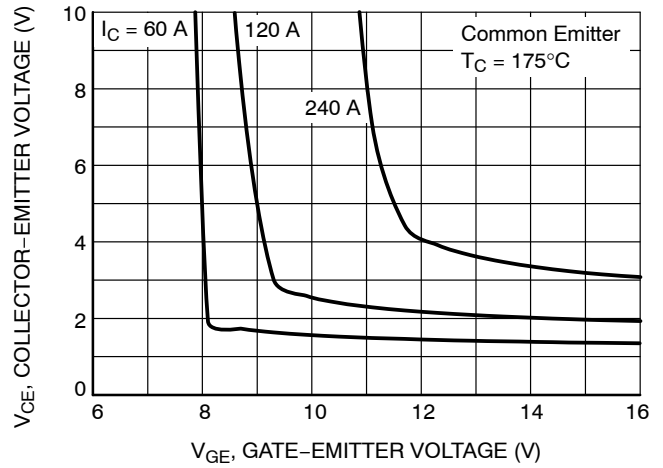


Figure 8. Saturation Voltage vs.  $V_{CE}$

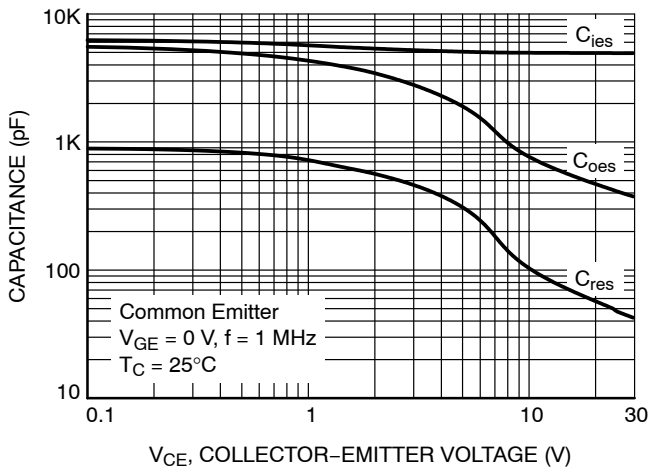


Figure 9. Capacitance Characteristics

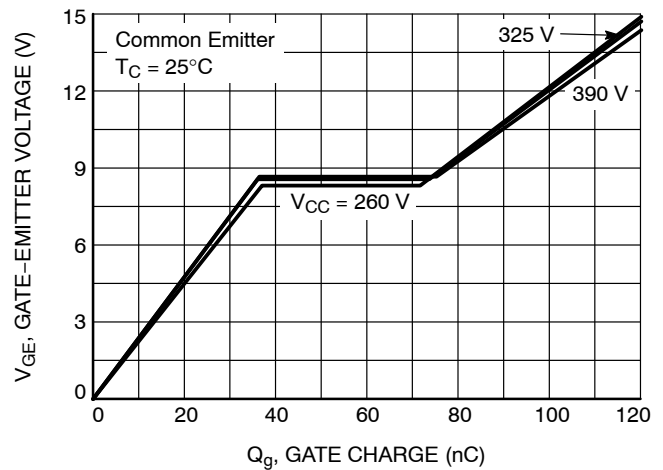


Figure 10. Gate Charge Characteristics

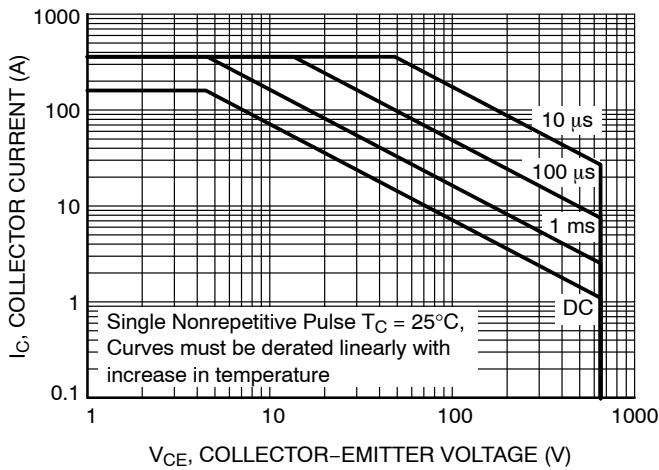


Figure 11. SOA Characteristics

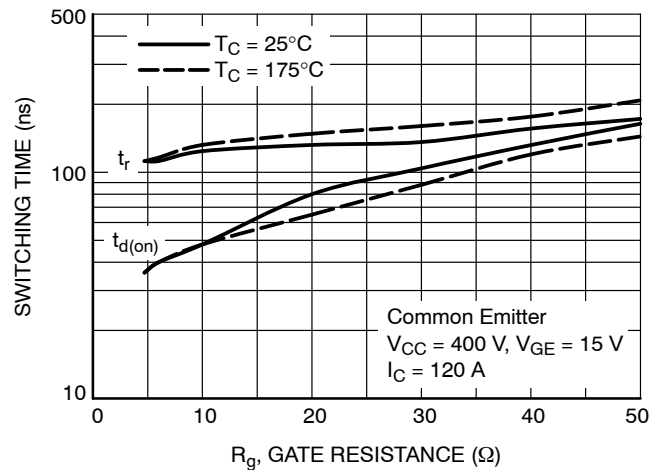


Figure 12. Turn-On Characteristics vs. Gate Resistance

TYPICAL CHARACTERISTICS

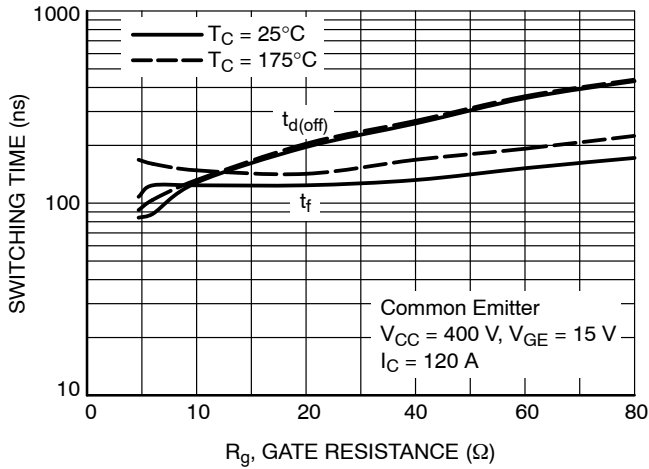


Figure 13. Turn-Off Characteristics vs. Gate Resistance

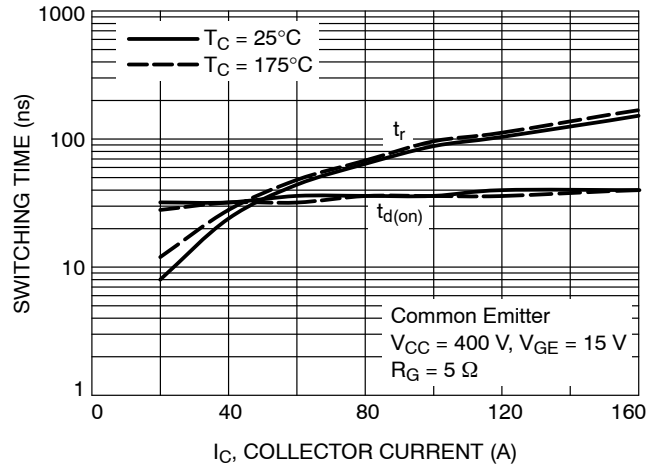


Figure 14. Turn-On Characteristics vs. Collector Current

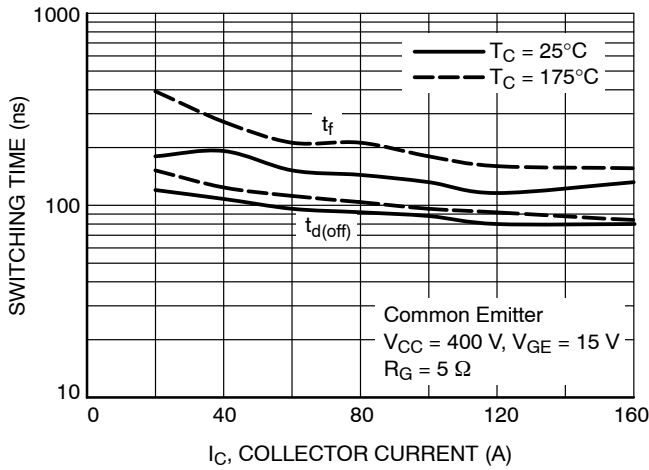


Figure 15. Turn-Off Characteristics vs. Collector Current

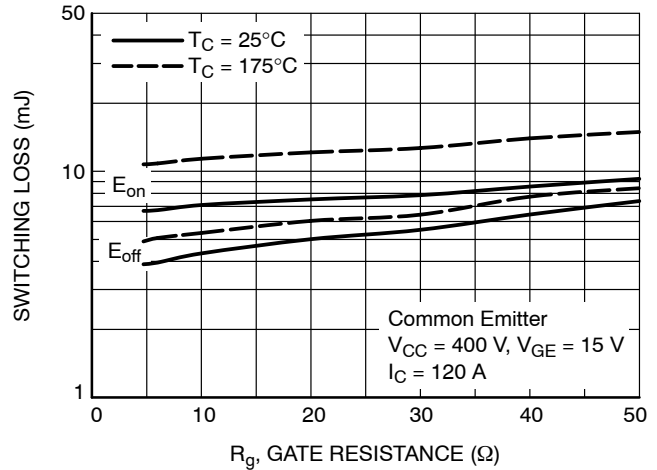


Figure 16. Switching Loss vs. Gate Resistance

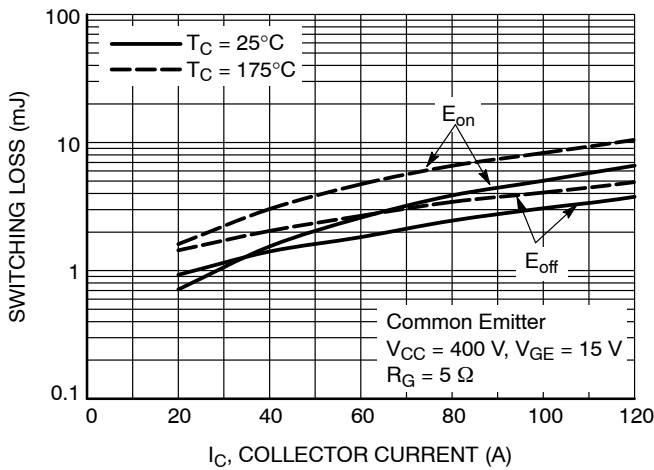


Figure 17. Switching Loss vs. Collector Current

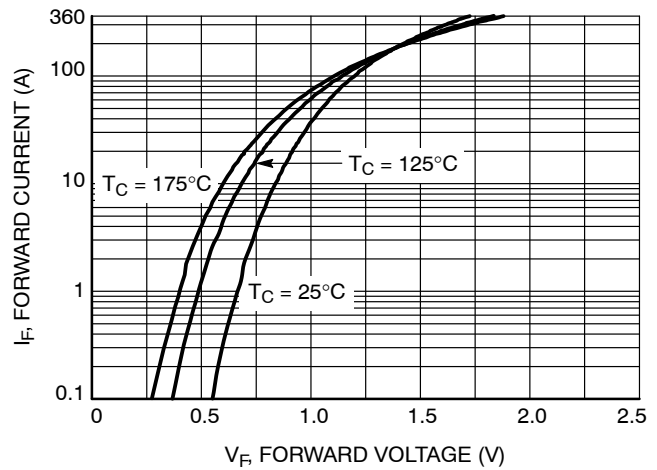


Figure 18. Forward Characteristics

TYPICAL CHARACTERISTICS

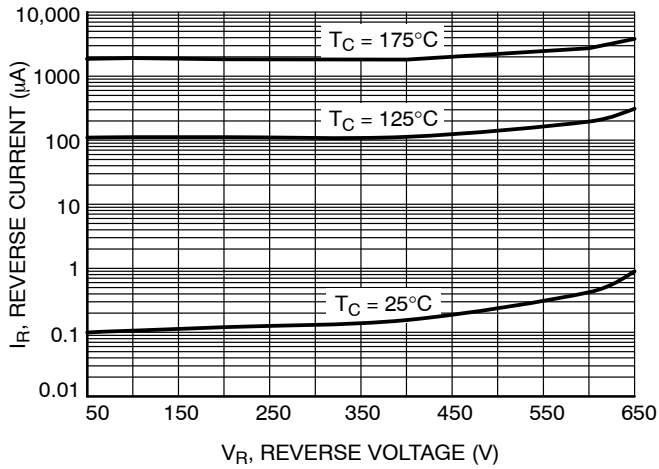


Figure 19. Reverse Current

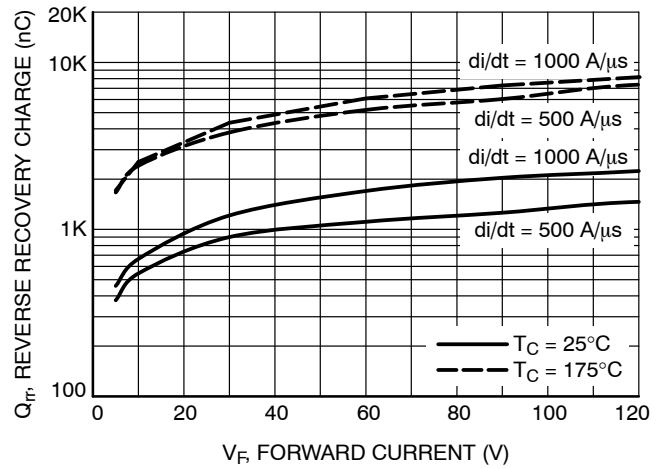


Figure 20. Stored Charge

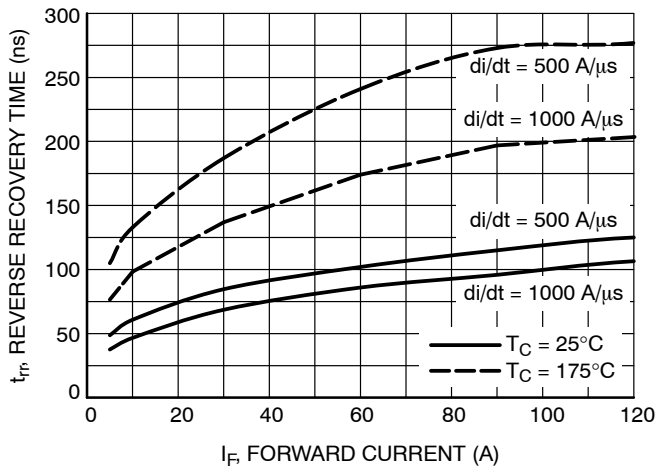


Figure 21. Reverse Recovery Time

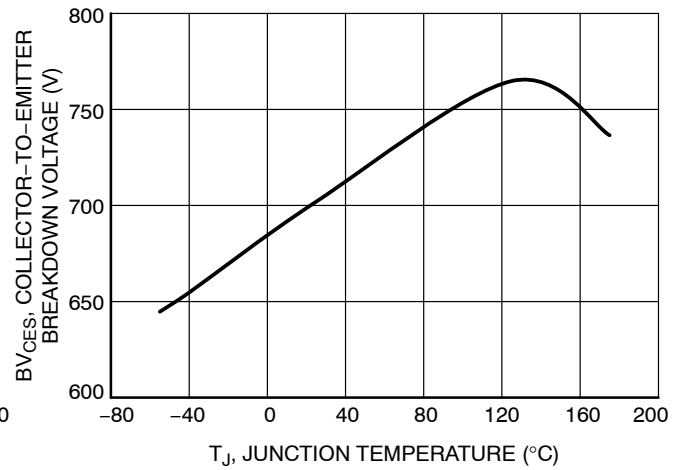


Figure 22. Collector-to-Emitter Breakdown Voltage vs. Junction Temperature

TYPICAL CHARACTERISTICS

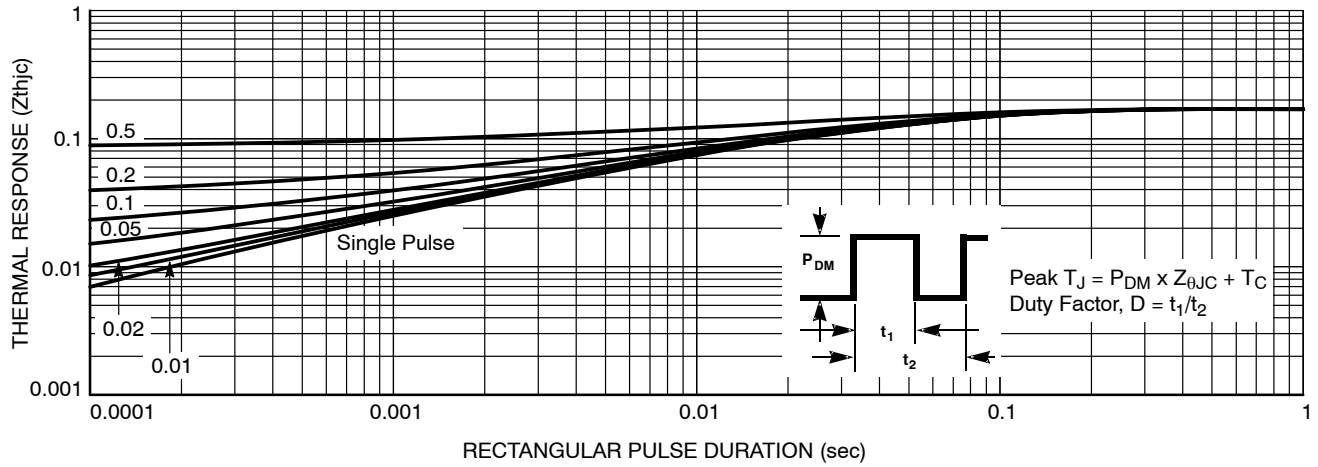


Figure 23. Transient Thermal Impedance of IGBT

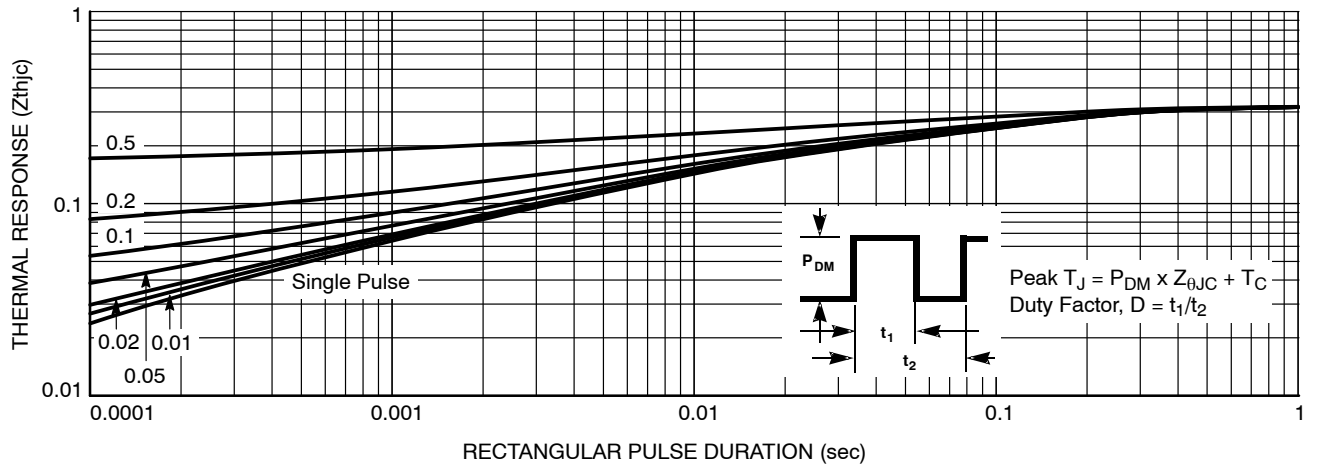
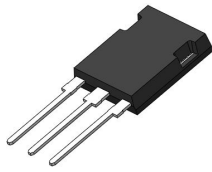


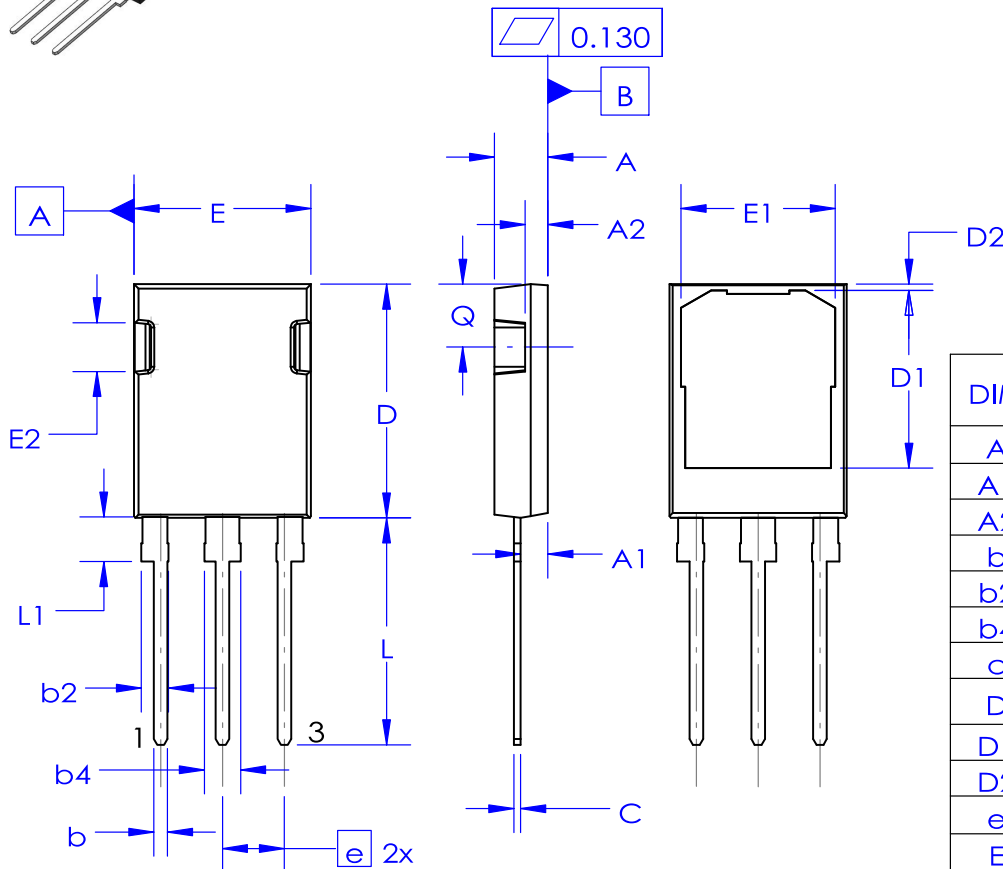
Figure 24. Transient Thermal Impedance of Diode





**TO-247-3LD**  
**CASE 340CU**  
**ISSUE B**

DATE 28 OCT 2021

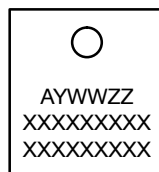


DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.60	4.70	4.80
A1	2.10	2.40	2.70
A2	1.70	2.00	2.30
b	1.16	1.20	1.26
b2	2.20	2.40	2.60
b4	3.00	3.20	3.40
c	0.59	0.60	0.66
D	20.40	20.60	20.80
D1	15.47	15.67	15.87
D2	0.25	0.55	0.85
e	5.45 BSC		
E	15.40	15.60	15.80
E1	13.40	13.60	13.80
E2	4.12	4.30	4.52
L	19.70	20.00	20.30
L1	3.65	3.85	4.05
Q	5.35	5.55	5.75

**NOTES:**

- A. NO INDUSTRY STANDARDS APPLIES TO THIS PACKAGE.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DRAWING CONFORMS TO ASME Y14.5-2009.

**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
A = Assembly Site Code  
Y = Year  
WW = Work Week  
ZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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